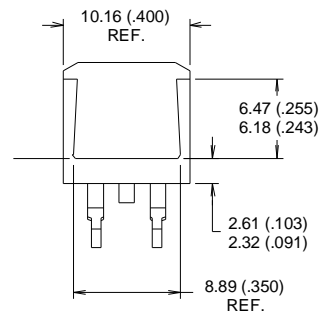
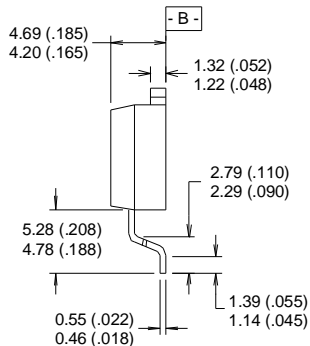
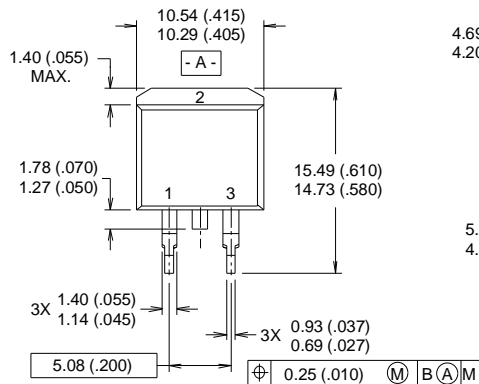


Package Outline

HEXFET TO-263AB Outline

Dimensions are shown in millimeters (inches)



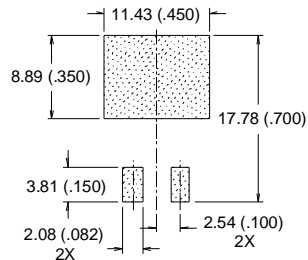
MINIMUM RECOMMENDED FOOTPRINT

NOTES:

- 1 DIMENSIONS AFTER SOLDER DIP.
- 2 DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982.
- 3 CONTROLLING DIMENSION : INCH.
- 4 HEATSINK & LEAD DIMENSIONS DO NOT INCLUDE BURRS.

LEAD ASSIGNMENTS

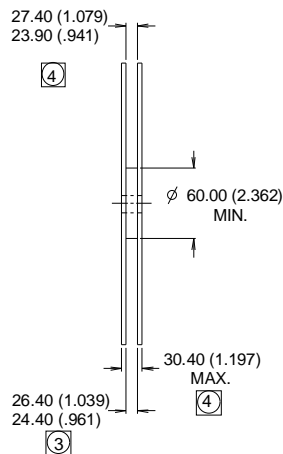
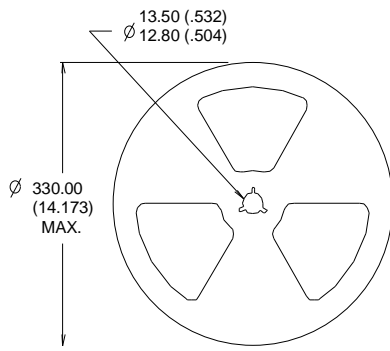
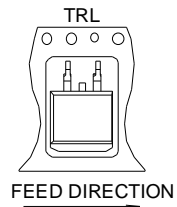
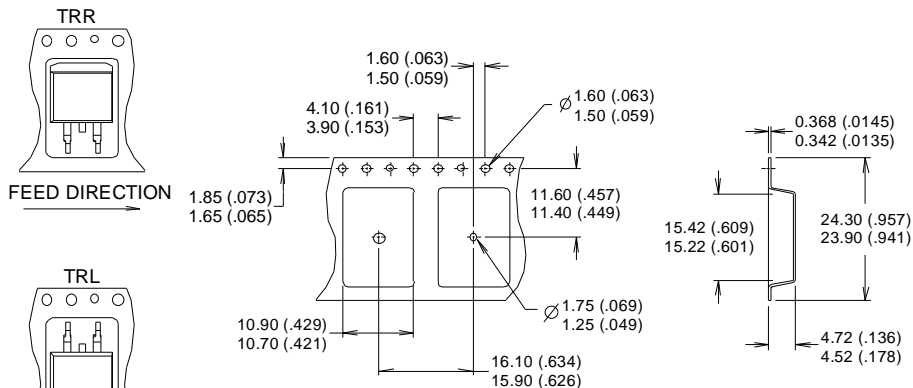
- 1 - GATE
- 2 - DRAIN
- 3 - SOURCE



Tape & Reel Information

HEXFET TO-263AB

Dimensions are shown in millimeters (inches)



NOTES :

1. CONFORMS TO EIA-418.
2. CONTROLLING DIMENSION: MILLIMETER.
- ③ DIMENSION MEASURED @ HUB.
- ④ INCLUDES FLANGE DISTORTION @ OUTER EDGE.

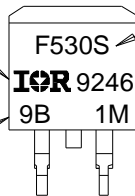
Part Marking Information

HEXFET TO-263AB

EXAMPLE : THIS IS AN IRF530S
WITH ASSEMBLY
LOT CODE 9B1M

INTERNATIONAL
RECTIFIER
LOGO

ASSEMBLY
LOT CODE



PART NUMBER

DATE CODE
(YYWW)
YY = YEAR
WW = WEEK